

General Description

The HXT8201 VCSEL driver is a key component for compact, robust, low-power optical transmitter modules. In conjunction with the VCSEL, the chip handles the complete digital-to-optical conversion, including CML input, laser driver, drive control, and supervision. Standard silicon technology and a small number of additional components allow for cost-effective and compact assemblies.

Applications

- 100G to 25G Ethernet SR Fan-out Modules
- 25G Ethernet SR / 32G Fibre Channel
- InfiniBand 25G EDR Transceivers / AOC
- Proprietary multi-channel optical modules

Features

- Low power consumption of 118mW per channel while delivering 5mA average and 5mA modulation current
- User selectable: Input equalization, output peaking, polarity inversion, interrupt masks
- Compatible with common cathode and isolated VCSEL arrays
- 2-wire, I²C compatible control interface
- Up to 10mA I_{AVG} and 10mA I_{MOD} current
- Suitable for TO Can applications
- SFP MSA Compatible

Ordering Information

Part	Temp Range	Pin-Package
HXT8201-DNT	0°C to +85°C	Bare Die* 1105 x 900µm
HXT8201-EVB	Room Temp	Evaluation Board

* Nominal Size: Actual die size may be slightly larger/smaller

For price, delivery schedules, and to place orders, please contact IDT: www.IDT.com/go/sales

Device Diagram

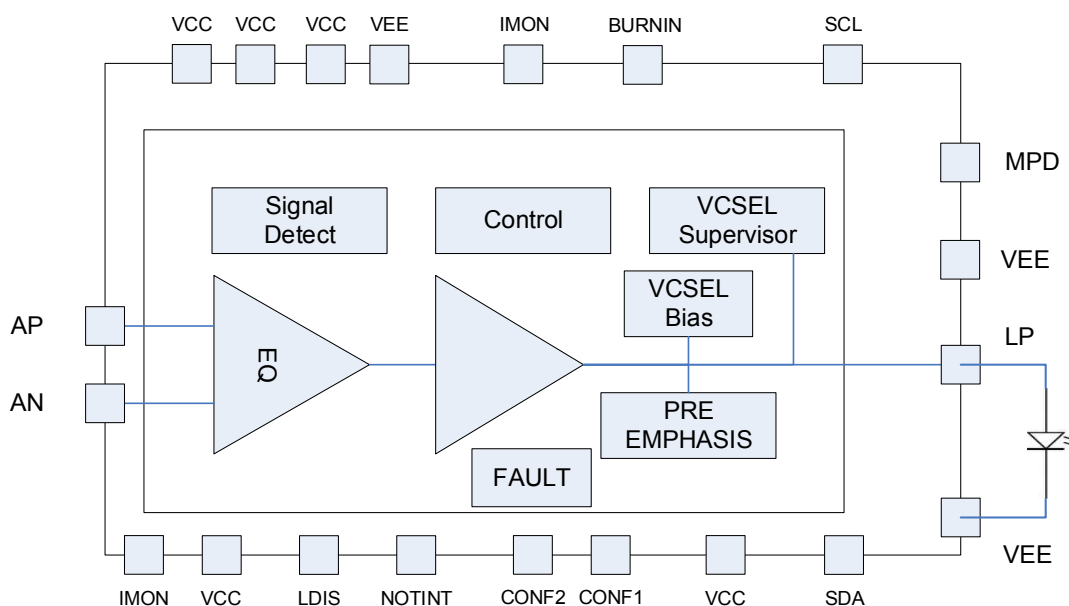


Figure 1: Device Diagram

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